In The Claims

Please cancel claims 1-36, without prejudice or disclaimer and add the following new claims 37-52:

37. (New) A circuit component built-in module comprising:

an insulating substrate formed of a mixture comprising an inorganic filler and a thermosetting resin;

a plurality of wiring patterns formed on at least one principal plane of the insulating substrate;

an active component buried in the insulating substrate and electrically connected to at least one of the wiring patterns; and

a passive component buried in the insulating substrate and electrically connected to at least one of the wiring patterns;

wherein the active component is electrically connected to the passive component by the wiring patterns.

38. (New) A circuit component built-in module according to claim 37, comprising an inner via formed in the insulating substrate and electrically connected to the wiring patterns.

39. (New) A circuit component built-in module according to claim 37, wherein 70 wt % to 95 wt % of the mixture comprises the inorganic filler and the thermosetting resin.

40.(New) A circuit component built-in module according to claim 37, wherein the wiring patterns are formed on the principal plane and in an internal portion of the insulating substrate.

41. (New) A circuit component built-in module according to claim 38, wherein the inner via is formed of a conductive resin composition.

42. (New) A circuit component built-in module according to claim 37, wherein the circuit component is shielded from external air by the insulating substrate.

43. (New) A circuit component built-in module according to claim 37, wherein the thermosetting resin comprises at least one thermosetting resin selected from the group consisting of an epoxy resin, a phenol resin and a cyanate resin.

44. (New) A circuit component built-in module according to claim 37, wherein the inorganic filler comprises at least one inorganic filler selected from the group consisting of Al_2O_3, MgO, BN, AlN and SiO_2.

45. (New) A circuit component built-in module according to claim 37, wherein an average particle diameter of the inorganic filler is 0.1μm to 100μm.

46. (New) A circuit component built-in module according to claim 37, wherein the wiring patterns comprise at least one conductive substance selected from the group consisting of copper and a conductive resin composition.

47. (New) A circuit component built-in module according to claim 37, wherein the wiring patterns comprise lead frames formed by etching or stamping.

48. (New) A circuit component built-in module according to claim 37, wherein the circuit component comprises at least one component selected from the group consisting of a chip resistor, a chip capacitor and a chip inductor.

49. (New) A circuit component built-in module according to claim 37, wherein the mixture further comprises at least one additive selected from the group consisting of a dispersant, a coloring agent, a coupling agent and a releasing agent.

50. (New) A circuit component built-in module according to claim 37, wherein the insulating substrate has a coefficient of linear expansion of 8×10^{-6}/°C to 20×10^{-6}/°C and a heat conductivity of 1w/mK to 10w/mK.

51. (New) A circuit component built-in module according to claim 37, wherein the active component comprises a semiconductor bare chip, and the semiconductor bare chip is flip-chip bonded onto the wiring pattern.

52. (New) A circuit component built-in module according to claim 37, wherein the conductive resin composition comprises metal particles of at least one metal selected from the group consisting of gold, silver, copper and nickel as a conductive component, and an epoxy resin as a resin component.